

Title (en)

COMPOSITE MOLDING AND PRODUCTION METHOD THEREFOR

Title (de)

VERBUNDSTOFFFORMVERFAHREN UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

MOULAGE COMPOSITE ET PROCÉDÉ DE PRODUCTION POUR CELUI-CI

Publication

EP 3835058 A4 20211006 (EN)

Application

EP 19846851 A 20190808

Priority

- JP 2018151386 A 20180810
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Abstract (en)

[origin: EP3835058A1] The present invention provides a composite molded body in which a rubber layer in the form of a thin film is formed on a surface of a resin molded body and a production method therefor. According to an embodiment of the present invention, a liquid composition containing a rubber component such as a rubber latex and a peroxide is applied to a surface of a resin molded body such as a polyamide-based resin having an amino group, causing crosslinking to occur in an uncrosslinked rubber layer and forming a crosslinked rubber layer in the form of a thin film. When a co-crosslinking agent is used in combination, adhesion to the resin molded body can be improved even when the thickness of the crosslinked rubber layer is small.

IPC 8 full level

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Citation (search report)

[X1] US 5132182 A 19920721 - GROSSE-PUPPENDAHL THOMAS [DE], et al

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